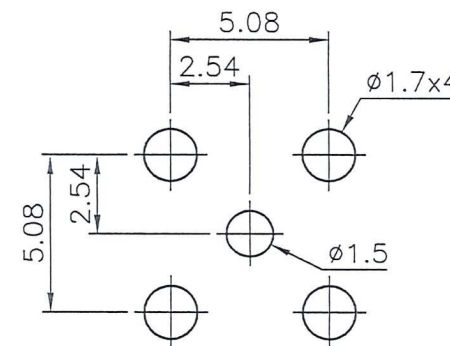
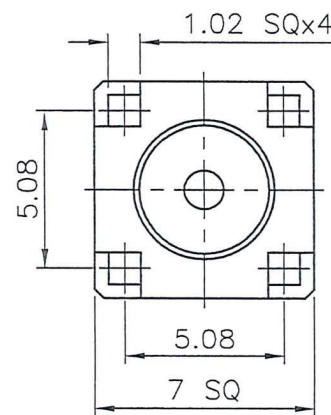
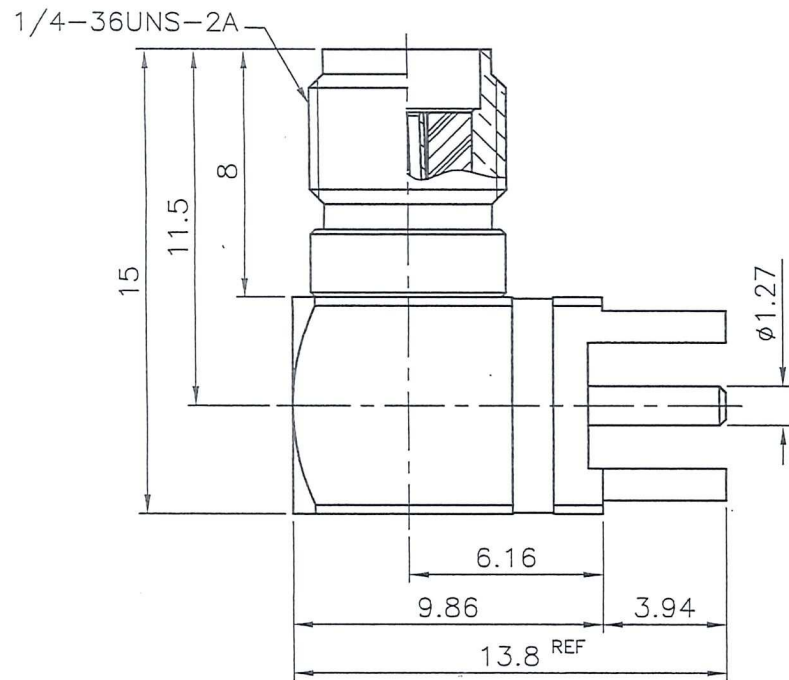
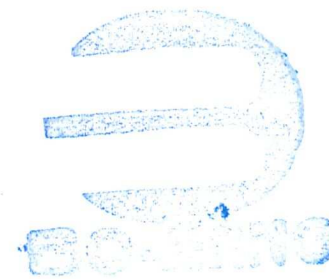


FOR CUSTOMER(WEB)

REVISIONS		
ISS	SYMBOL	DESCRIPTION\DATE
A2		訂正視圖 \07/30/12'
A3		依據連絡單 CL-170724AC01, 1 SQx4 變更為 1.02 SQx4 \08/06/18'



P.C.B. LAYOUT
(印刷电路板配置)

NOTES: FINISH (PLATING THICKNESS IN MICRO-INCHES)

1. BRASS PER QQ-B-626
2. GOLD PL 3 MIN OVER NICKEL PL 70 MIN THICK OVER COPPER STRIKE
3. BERYLLIUM COPPER PER QQ-C-530
4. GOLD PL 30 MIN OVER NICKEL PL 70 MIN THICK OVER COPPER STRIKE



HSF COMPLIANT

					DIMENSIONS ARE IN MILLIMETERS			PART NO.	
					UNLESS OTHERWISE SPECIFIED TOLERANCES (一般公差)			APPROVED DATE	
INSULATOR	PTFE	WHITE			0.5~6 = ±0.2				08/06/18'
INSULATOR	PTFE	WHITE			>6~30 = ±0.4			CHECKED	DATE
BODY	NOTE 1	NOTE 2			>30~120 = ±0.6				08/06/18'
CONTACT PIN	NOTE 3	NOTE 4			>120~315 = ±1			DRAWN	DATE
CUBE BODY	NOTE 1	NOTE 2			>315~1000 = ±1.6				08/06/18'
					ANGLES(角度) = ±5°				
NO.	DESCRIPTION	MATERIAL	FINISH	Q'TY	DRAWING NO.	SCALE	4/1	ISSUE	A3

BO-JIANG

帛江科技股份有限公司
BO-JIANG TECHNOLOGY CO., LTD.

TITLE	SMA R/A PCB JACK
DRAWING NO.	7865NR502BD000B
FILE NO.	Z:\NND\7865\NR\502\000\7865NR502BD000B-A3